

# Ultrafast Rectifier, 4 A FRED Pt®

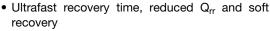




SMB (DO-214AA)

PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	4 A			
$V_{R}$	600 V			
V <sub>F</sub> at I <sub>F</sub>	0.94 V			
t <sub>rr</sub> typ.	45 ns			
T <sub>J</sub> max.	175 °C			
Package	SMB (DO-214AA)			
Circuit configuration	Single			

#### **FEATURES**





RoHS

COMPLIANT **HALOGEN** 

FREE

- 175 °C maximum operating junction temperature
- For PFC CRM/CCM, snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Designed and qualified according to JEDEC®-JESD 47
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

#### **DESCRIPTION / APPLICATIONS**

State of the art ultrafast recovery rectifiers designed with optimized performance of forward voltage drop, ultrafast recovery time, and fast recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Peak repetitive reverse voltage	$V_{RRM}$		600	V	
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>L</sub> = 103 °C <sup>(1)</sup>	4	۸	
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C, 6 ms square pulse	100	А	
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C	

#### Note

<sup>(1)</sup> Mounted on PCB with minimum pad size

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_{R}$	I <sub>R</sub> = 100 μA	600	-	-	.,
Forward voltage	V <sub>F</sub>	$I_F = 4 A$	-	1.12	1.3	V
Torward voitage	٧F	I <sub>F</sub> = 4 A, T <sub>J</sub> = 150 °C	-	0.94	1.15	
Reverse leakage current I <sub>R</sub>	$V_R = V_R$ rated	-	-	3		
	'R	$T_J = 150 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	-	100	<del>-</del> μΑ
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	6.8	-	pF



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt = 100 A/μs, V <sub>R</sub> = 30 V		-	45	-	ns
		$I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	50	-	
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1 A, I <sub>rr</sub> = 0.25 A		-	-	65	
		T <sub>J</sub> = 25 °C		-	39	-	
		T <sub>J</sub> = 125 °C		-	61	-	
Peak recovery current I <sub>RRM</sub>	I	T <sub>J</sub> = 25 °C	$I_F = 4 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 390 \text{ V}$	-	5.8	-	Α
	IRRM	T <sub>J</sub> = 125 °C		-	7.7	-	
Reverse recovery charge Q <sub>rr</sub>	0	T <sub>J</sub> = 25 °C		-	119	-	nC
	T <sub>J</sub> = 125 °C		-	251	-	TIC	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55	-	+175	°C
Thermal resistance, junction to case	R <sub>thJC</sub> (1)		-	-	18	°C/W
Thermal resistance, junction to ambient	R <sub>thJA</sub> <sup>(1)</sup>		-	-	90	C/VV
Approximate Weight				0.1		g
Approximate Weight			0.003		OZ.	
Marking device		Case style SMB (DO-214AA)		41	J6	•

#### Note

<sup>(1)</sup> Mounted on PCB with minimum pad size

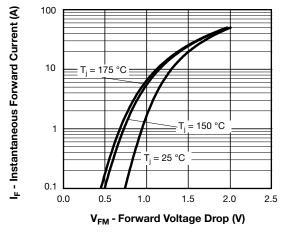


Fig. 1 - Typical Forward Voltage Drop Characteristics

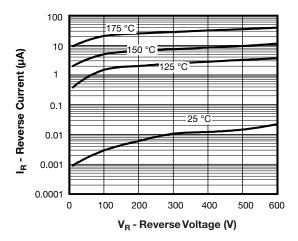


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

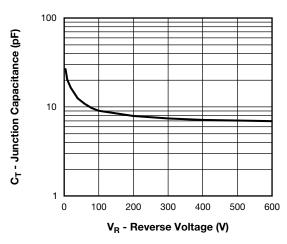


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

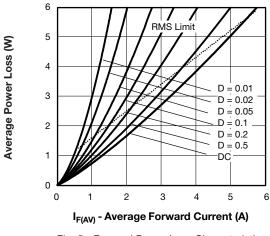


Fig. 5 - Forward Power Loss Characteristics

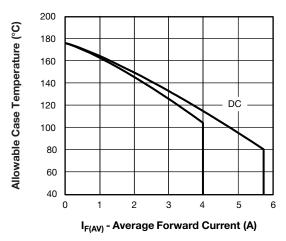


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

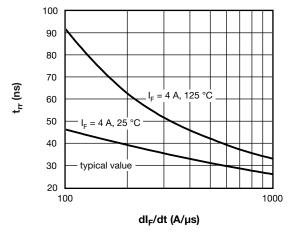


Fig. 6 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

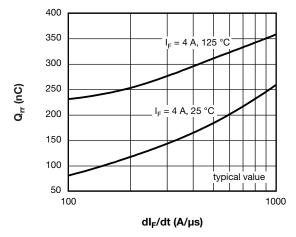
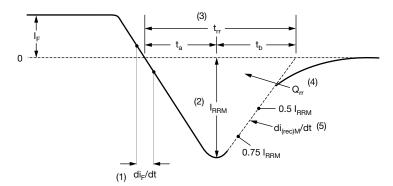


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
  - ro crossing and I<sub>RRM</sub>
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  area under curve defined by  $t_{rr}$  and  $I_{RRM}$

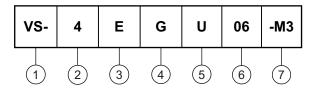
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 8 - Reverse Recovery Waveform and Definitions

#### **ORDERING INFORMATION TABLE**

Device code



- Vishay Semiconductors product
- 2 Current rating (4 = 4 A)
- 3 Circuit configuration:

E = single diode

4 - G = SMB package

**5** - Process type,

U = ultrafast recovery

6 - Voltage code (06 = 600 V)

7 - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-4EGU06-M3/5BT	5BT	3200	13"diameter plastic tape and reel		

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95401</u>				
Part marking information	www.vishay.com/doc?95472			
Packaging information	www.vishay.com/doc?95404			



## **SMB**

### **DIMENSIONS** in inches (millimeters)

### DO-214AA (SMB)



### **Mounting Pad Layout**





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Vishay

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